

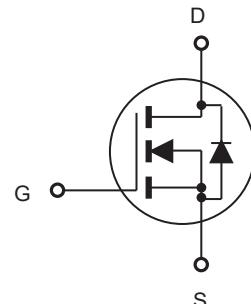


CEP60N60SF/CEB60N60SF CEF60N60SF

N-Channel Enhancement Mode Field Effect Transistor With Fast Body Diode

FEATURES

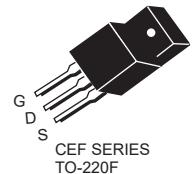
Type	$V_{DSS}@T_J \text{ max}$	$R_{DS(\text{ON})}$	I_D	@ V_{GS}
CEP60N60SF	650V	37mΩ	60A	10V
CEB60N60SF	650V	37mΩ	60A	10V
CEF60N60SF	650V	37mΩ	60A ^d	10V



- Super high dense cell design for extremely low $R_{DS(\text{ON})}$.
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- Fast reverse recovery time.

Applications

- PV Inverter.
- EV Charging.
- SMPS.



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V_{DS}	600		V
Gate-Source Voltage	V_{GS}	± 30		V
Drain Current-Continuous @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	I_D	60	60 ^d	A
		38	38 ^d	A
Drain Current-Pulsed ^a	I_{DM}^e	240	240 ^d	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	P_D	329	89	W
		2.63	0.71	W/°C
Single Pulsed Avalanche Energy ^g	E_{AS}	364.5		mJ
Single Pulsed Avalanche Current ^g	I_{AS}	9		A
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	R_{JC}	0.38	1.4	°C/W
Thermal Resistance, Junction-to-Ambient	R_{JA}	62.5	65	°C/W



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units	
Off Characteristics							
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	600			V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}$			5	μA	
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA	
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA	
On Characteristics ^b							
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	3		5	V	
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		31	37	$\text{m}\Omega$	
Gate input resistance	R_g	f=1MHz,open Drain		1.8		Ω	
Dynamic Characteristics ^c							
Input Capacitance	C_{iss}	$V_{\text{DS}} = 400\text{V}, V_{\text{GS}} = 0\text{V}, f = 250\text{KHz}$		3455		pF	
Output Capacitance	C_{oss}			110		pF	
Reverse Transfer Capacitance	C_{rss}			20		pF	
Switching Characteristics ^c							
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 400\text{V}, I_D = 16\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 5.3\Omega$		57		ns	
Turn-On Rise Time	t_r			10		ns	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			132		ns	
Turn-Off Fall Time	t_f			10		ns	
Total Gate Charge	Q_g	$V_{\text{DS}} = 400\text{V}, I_D = 16\text{A}, V_{\text{GS}} = 10\text{V}$		130		nC	
Gate-Source Charge	Q_{gs}			33		nC	
Gate-Drain Charge	Q_{gd}			54		nC	
Drain-Source Diode Characteristics and Maximum Ratings							
Drain-Source Diode Forward Current	I_S ^f	$V_{\text{GS}} = 0\text{V}, I_S = 20\text{A}$			60	A	
Drain-Source Diode Forward Voltage ^b	V_{SD}				1.5	V	
Reverse Recovery Time	T_{rr}			195		ns	
Reverse Recovery Charge	Q_{rr}			1.31		uC	
Peak Reverse Recovery Current	I_{rr}			13		A	
Notes :							
a.Repetitive Rating : Pulse width limited by maximum junction temperature .							
b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$. Duty Cycle $\leq 2\%$.							
c.Guaranteed by design, not subject to production testing.							
d.Limited only by maximum temperature allowed .							
e.Pulse width limited by safe operating area .							
f.Full package $I_S(\text{max}) = 31\text{A}$.							
g.L = 9mH, $I_{\text{AS}} = 9\text{A}$, $V_{\text{DD}} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.							



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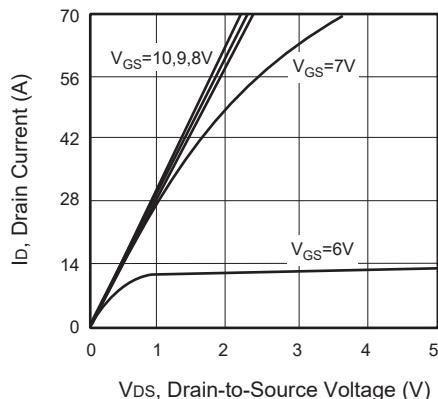


Figure 1. Output Characteristics

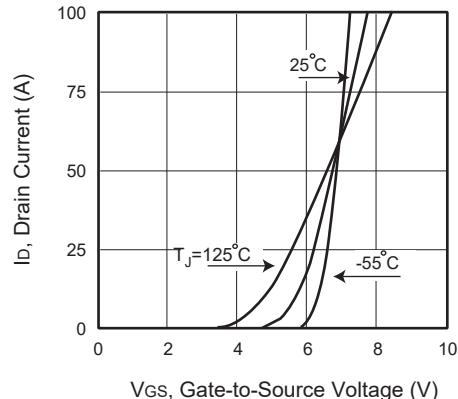


Figure 2. Transfer Characteristics

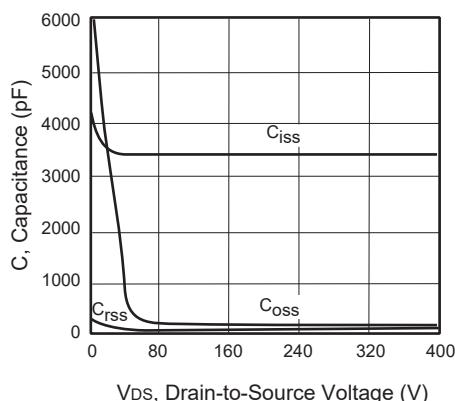


Figure 3. Capacitance

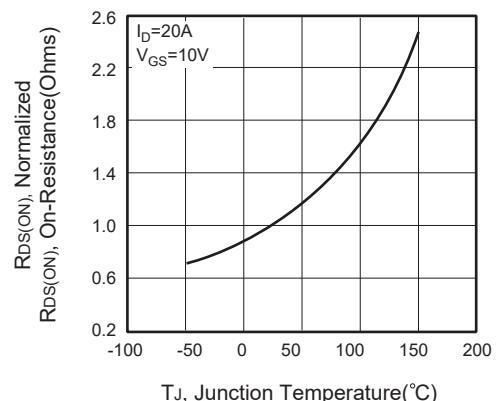


Figure 4. On-Resistance Variation with Temperature

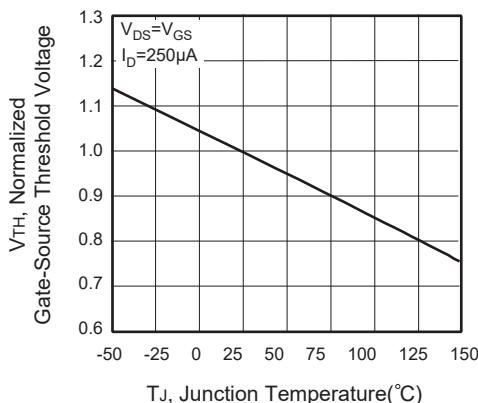


Figure 5. Gate Threshold Variation with Temperature

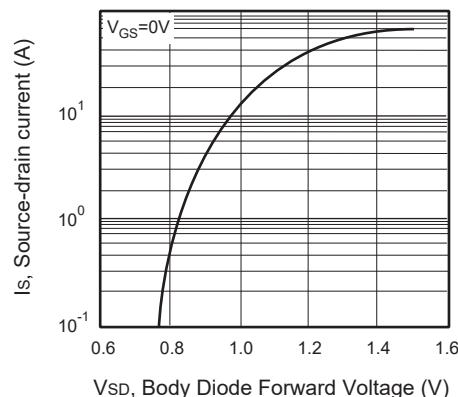


Figure 6. Body Diode Forward Voltage Variation with Source Current



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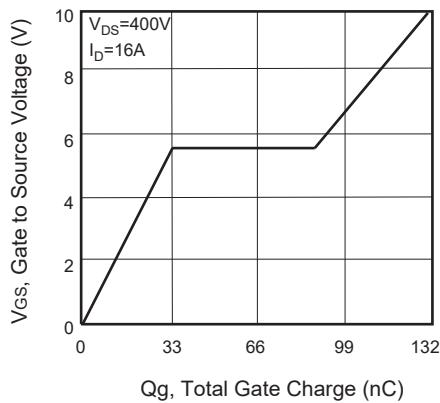


Figure 7. Gate Charge

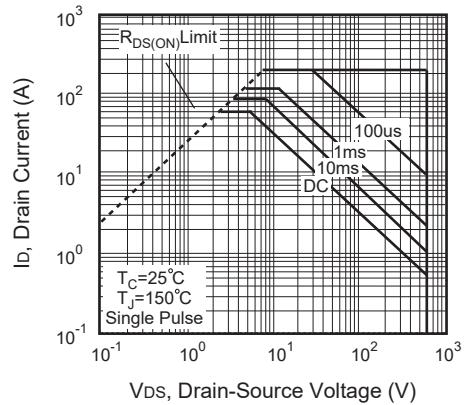


Figure 8. Maximum Safe
Operating Area

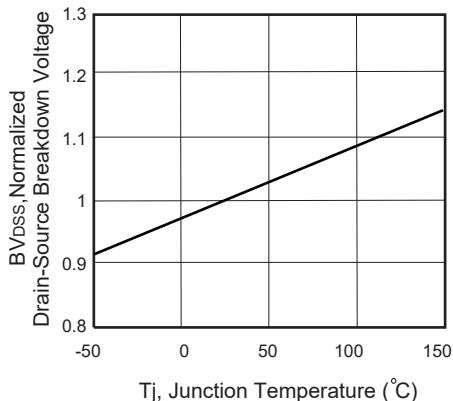


Figure 9. Breakdown Voltage Variation
VS Temperature

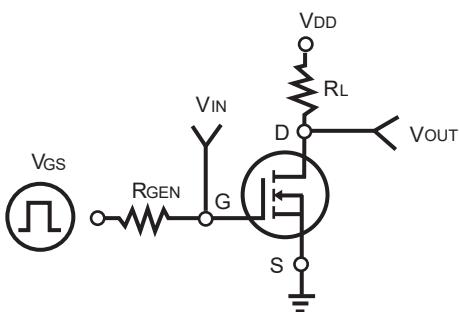


Figure 10. Switching Test Circuit

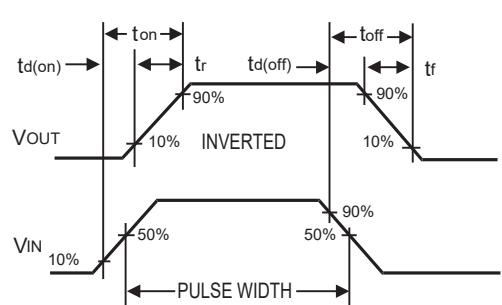


Figure 11. Switching Waveforms



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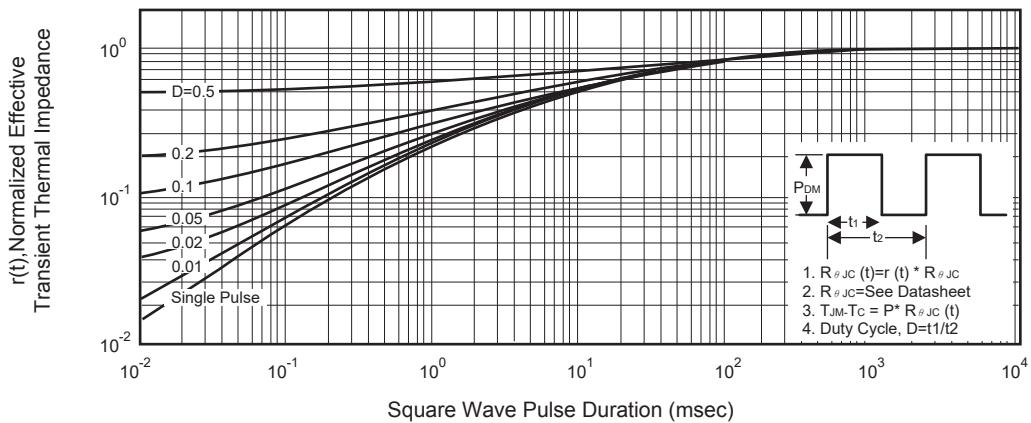


Figure 12. Normalized Thermal Transient Impedance Curve